

Part Number: XZMDK54W-4

 $2.0\mathrm{x}1.25\mathrm{mm}$ SMD CHIP LED LAMP

PRELIMINARY SPEC

Features

- 2.0X1.25mm SMT LED,0.5mm MAX.THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE: 2000PCS/REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- Rohs Compliant.

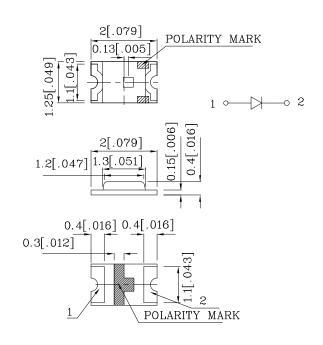




Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.1(0.004") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)		MDK (InGaAlP)	Unit	
Reverse Voltage	VR	5	V	
Forward Current	IF	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	185	mA	
Power Dissipation	Рт	75	mW	
Operating Temperature	TA	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		



Operating Characteristic (TA=25°C)	MDK (InGaAlP)	Unit	
Forward Voltage (Typ.) (IF=20mA)	$V_{\rm F}$	1.95	V
Forward Voltage (Max.) (IF=20mA)	$V_{\rm F}$	2.5	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	650	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	635	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	28	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	35	pF

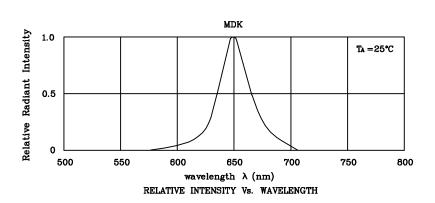
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZMDK54W-4	Red	InGaAlP	Water Clear	50	148	650	110°
Published Date : JAN 23,2008 Drawing No :XDSA6835		g No :XDSA6835	V3	3 Checked : B.L.LIU		P.1/4	



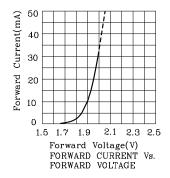
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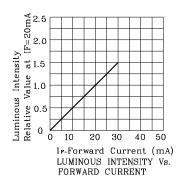
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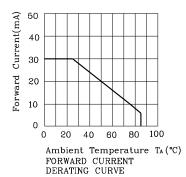


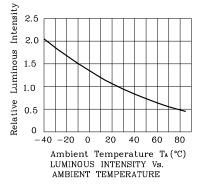


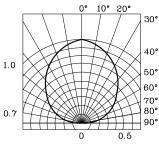
❖ MDK







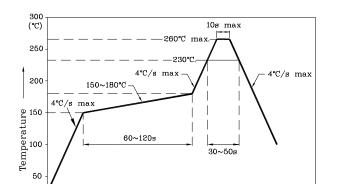




SPATIAL DISTRIBUTION

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Reflow Soldering Profile For Lead-free SMT Process.

Notes:

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- 1. Maximum soldering temperature should not exceed 260°C.
- 2. Recommended reflow temperature: 145°c-260°C.

Time

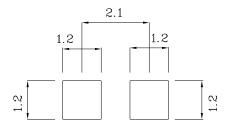
100

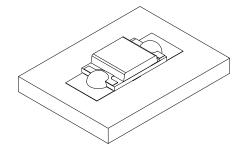
3.Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

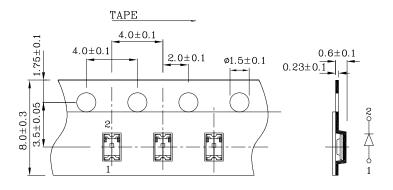
❖ The device has a single mounting surface. The device must be mounted according to the specifications.

250





❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

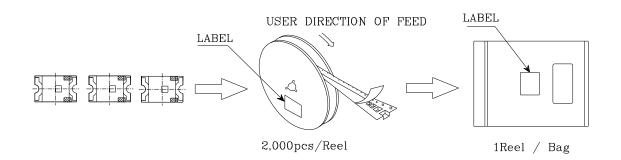


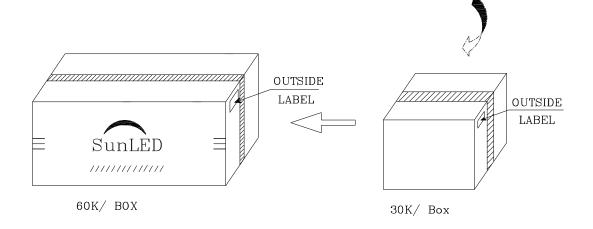
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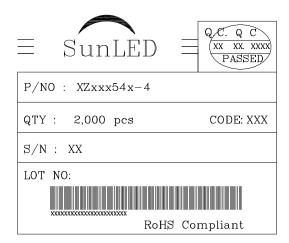
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PACKING & LABEL SPECIFICATIONS

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